

# MOSFET - Power, Single N-Channel, $\mu$ 8FL 60 V, 16.3 m $\Omega$ , 32 A

## NVTFS016N06C

### Features

- Small Footprint (3.3 x 3.3 mm) for Compact Design
- Low  $R_{DS(on)}$  to Minimize Conduction Losses
- Low  $Q_G$  and Capacitance to Minimize Driver Losses
- NVTFW016N06C – Wettable Flank Option for Enhanced Optical Inspection
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### Typical Applications

- Power Tools, Battery Operated Vacuums
- UAV/Drones, Material Handling
- BMS/Storage, Home Automation

### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-to-Source Voltage		V <sub>DSS</sub>	60	V
Gate-to-Source Voltage		V <sub>GS</sub>	$\pm 20$	V
Continuous Drain Current R <sub>θJC</sub> (Notes 1, 3)	Steady State	T <sub>C</sub> = 25°C	I <sub>D</sub>	32
		T <sub>C</sub> = 100°C		23
Power Dissipation R <sub>θJC</sub> (Note 1)		T <sub>C</sub> = 25°C	P <sub>D</sub>	36
		T <sub>C</sub> = 100°C		18
Continuous Drain Current R <sub>θJA</sub> (Notes 1, 2, 3)	Steady State	T <sub>A</sub> = 25°C	I <sub>D</sub>	8
		T <sub>A</sub> = 100°C		6
Power Dissipation R <sub>θJA</sub> (Notes 1, 2)		T <sub>A</sub> = 25°C	P <sub>D</sub>	2.5
		T <sub>A</sub> = 100°C		1.2
Pulsed Drain Current	T <sub>A</sub> = 25°C, t <sub>p</sub> = 10 $\mu$ s	I <sub>DM</sub>	160	A
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C
Source Current (Body Diode)		I <sub>S</sub>	30	A
Single Pulse Drain-to-Source Avalanche Energy (I <sub>L(pk)</sub> = 6.6 A)		E <sub>AS</sub>	22	mJ
Lead Temperature Soldering Reflow for Soldering Purposes (1/8" from case for 10 s)		T <sub>L</sub>	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

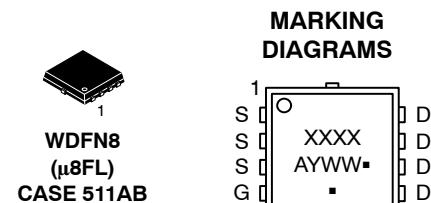
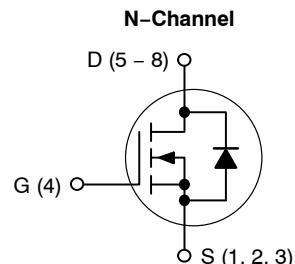
1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
2. Surface-mounted on FR4 board using a 650 mm<sup>2</sup>, 2 oz. Cu pad.
3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.



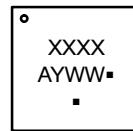
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V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> MAX	I <sub>D</sub> MAX
60 V	16.3 m $\Omega$ @ 10 V	32 A



WDFNW8  
(Full-Cut  $\mu$ 8FL)  
CASE 515AN



WDFN8  
(μ8FL)  
CASE 511AB

XXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

# NVTFS016N06C

## THERMAL RESISTANCE RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case – Steady State (Note 2)	$R_{\theta JC}$	4.1	°C/W
Junction-to-Ambient – Steady State (Note 2)	$R_{\theta JA}$	59.6	

4. Surface-mounted on FR4 board using a 650 mm<sup>2</sup>, 2 oz. Cu pad.

## ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0 \text{ V}$ , $I_D = 250 \mu\text{A}$	60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$	$I_D = 250 \mu\text{A}$ , referenced to 25°C		29		mV/°C
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0 \text{ V}$ , $V_{DS} = 60 \text{ V}$	$T_J = 25^\circ\text{C}$		10	$\mu\text{A}$
			$T_J = 125^\circ\text{C}$		250	
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{DS} = 0 \text{ V}$ , $V_{GS} = 20 \text{ V}$			100	nA

### ON CHARACTERISTICS (Note 5)

Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}$ , $I_D = 25 \mu\text{A}$	2.0		4.0	V
Negative Threshold Temperature Coefficient	$V_{GS(TH)}/T_J$	$I_D = 25 \mu\text{A}$ , referenced to 25°C		-8.2		mV/°C
Drain-to-Source On Resistance	$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$ , $I_D = 5 \text{ A}$		13.6	16.3	mΩ
Forward Transconductance	$g_{FS}$	$V_{DS} = 5 \text{ V}$ , $I_D = 5 \text{ A}$		15		S
Gate-Resistance	$R_G$	$T_A = 25^\circ\text{C}$		1.4		Ω

### CHARGES AND CAPACITANCES

Input Capacitance	$C_{iss}$	$V_{GS} = 0 \text{ V}$ , $f = 1 \text{ MHz}$ , $V_{DS} = 30 \text{ V}$		489		pF
Output Capacitance	$C_{oss}$			319		
Reverse Transfer Capacitance	$C_{rss}$			5.7		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 10 \text{ V}$ , $V_{DS} = 48 \text{ V}$ , $I_D = 5 \text{ A}$		6.9		nC
Threshold Gate Charge	$Q_{G(TH)}$			1.6		
Gate-to-Source Charge	$Q_{GS}$			2.6		
Gate-to-Drain Charge	$Q_{GD}$			0.62		

### SWITCHING CHARACTERISTICS (Note 6)

Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = 10 \text{ V}$ , $V_{DS} = 48 \text{ V}$ , $I_D = 5 \text{ A}$ , $R_G = 6 \Omega$		7.2		ns
Rise Time	$t_r$			1.7		
Turn-Off Delay Time	$t_{d(off)}$			11.1		
Fall Time	$t_f$			2.7		

### DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Diode Voltage	$V_{SD}$	$V_{GS} = 0 \text{ V}$ , $I_S = 5 \text{ A}$	$T_J = 25^\circ\text{C}$	0.81	1.2	V
			$T_J = 125^\circ\text{C}$	0.67		
Reverse Recovery Time	$t_{RR}$	$V_{GS} = 0 \text{ V}$ , $dI_S/dt = 100 \text{ A}/\mu\text{s}$ , $V_{DS} = 30 \text{ V}$ , $I_S = 5 \text{ A}$		27		ns
Charge Time	$t_a$			13		
Discharge Time	$t_b$			14		
Reverse Recovery Charge	$Q_{RR}$			15		

5. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.

6. Switching characteristics are independent of operating junction temperatures.

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## TYPICAL CHARACTERISTICS

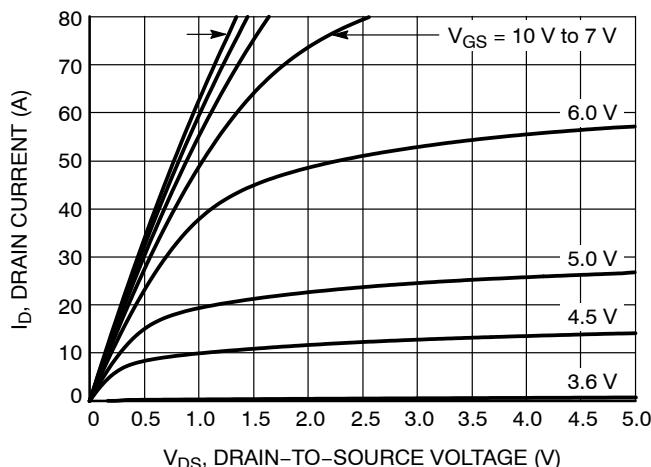


Figure 1. On-Region Characteristics

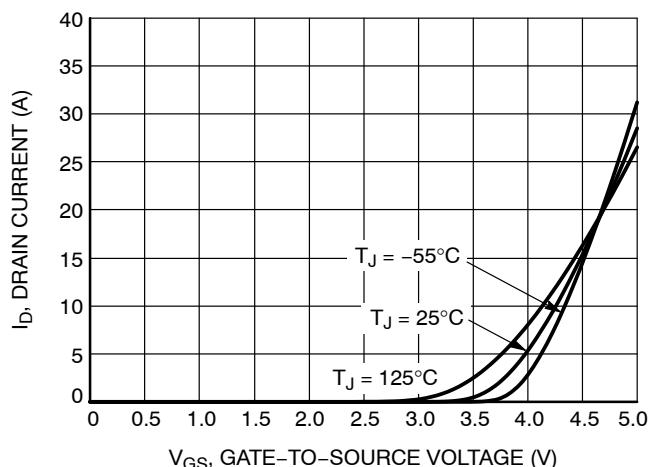


Figure 2. Transfer Characteristics

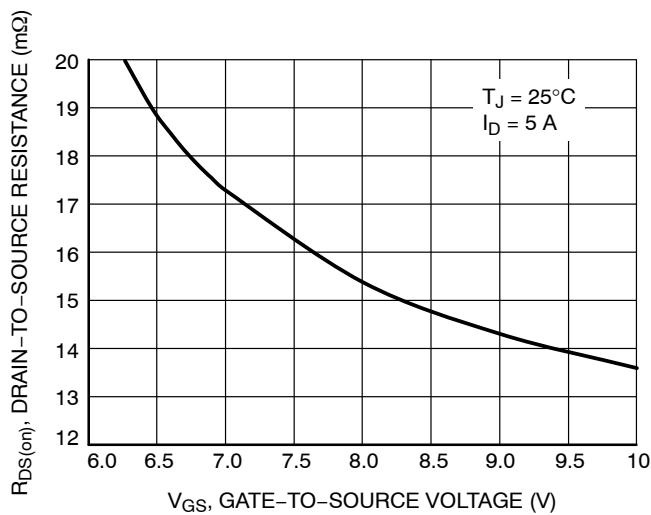


Figure 3. On-Resistance vs. Gate-to-Source Voltage

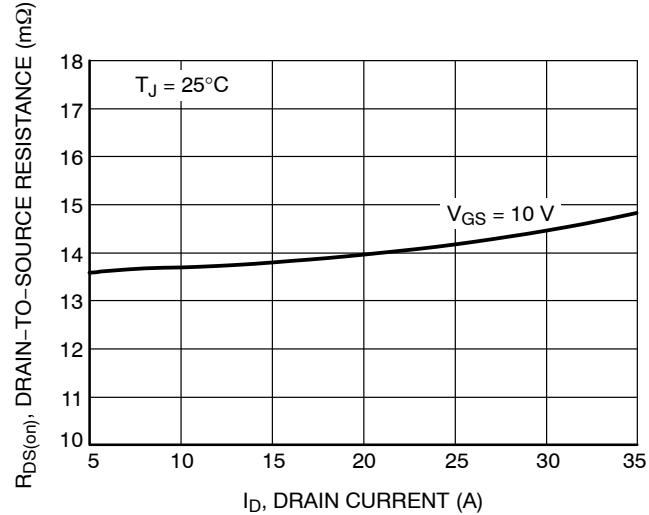


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

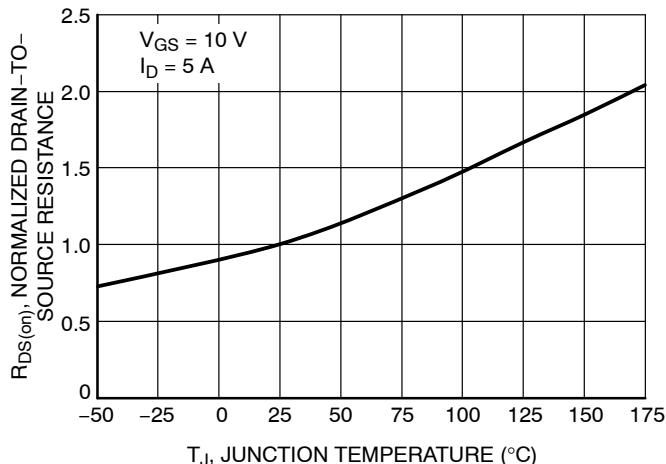


Figure 5. On-Resistance Variation with Temperature

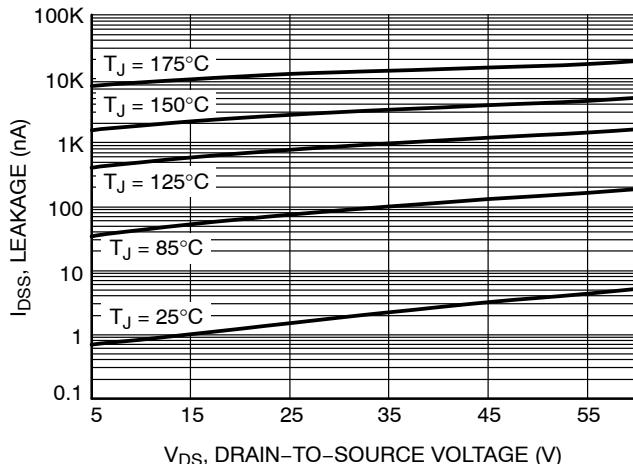


Figure 6. Drain-to-Source Leakage Current vs. Voltage

## TYPICAL CHARACTERISTICS

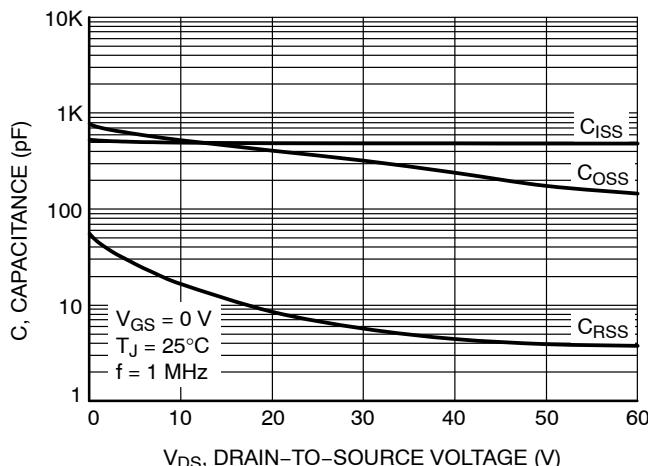


Figure 7. Capacitance Variation

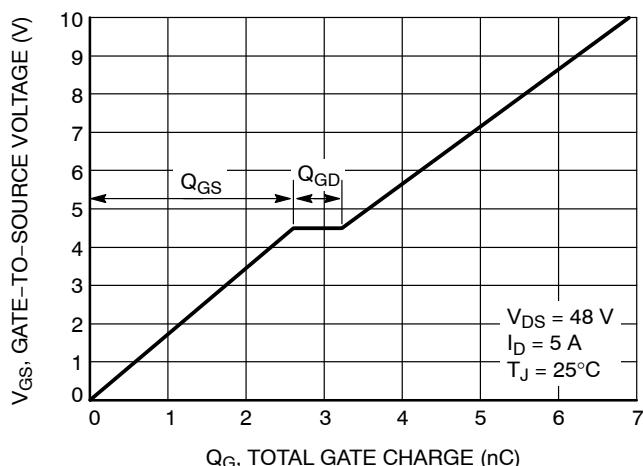


Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

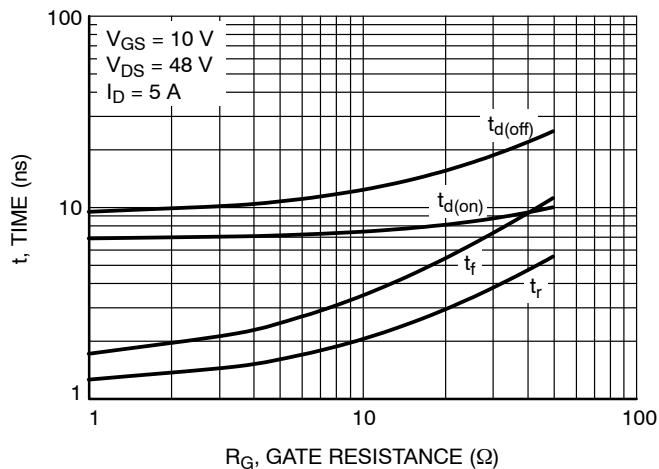


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

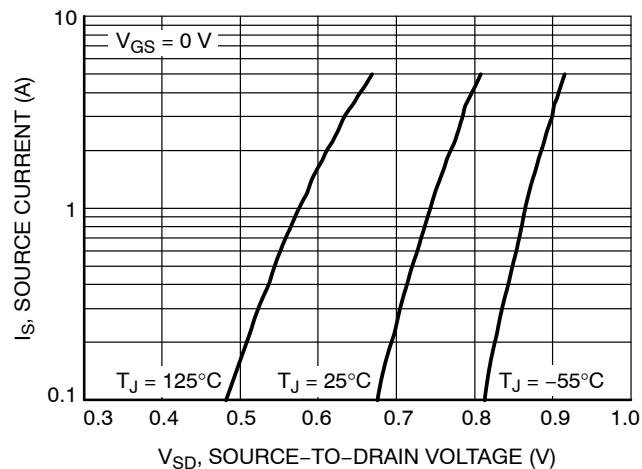


Figure 10. Diode Forward Voltage vs. Current

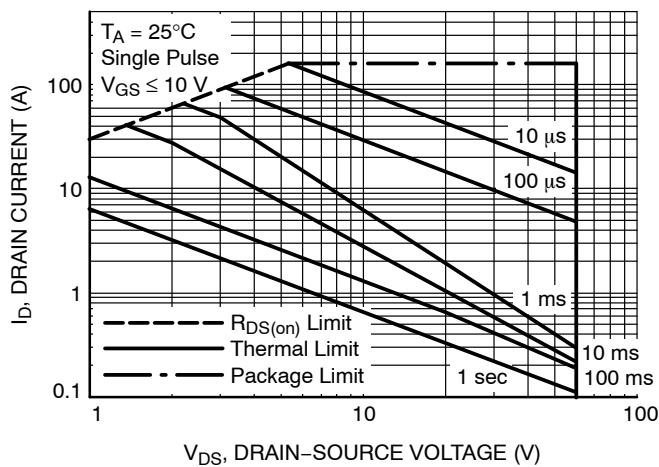


Figure 11. Safe Operating Area

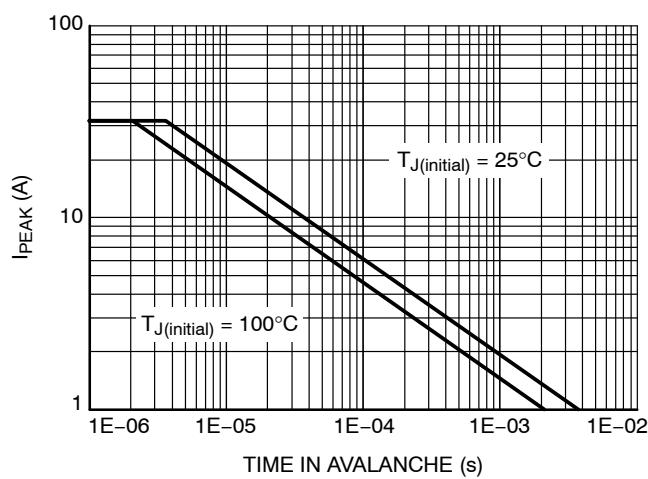


Figure 12. Maximum Drain Current vs. Time in Avalanche

## TYPICAL CHARACTERISTICS

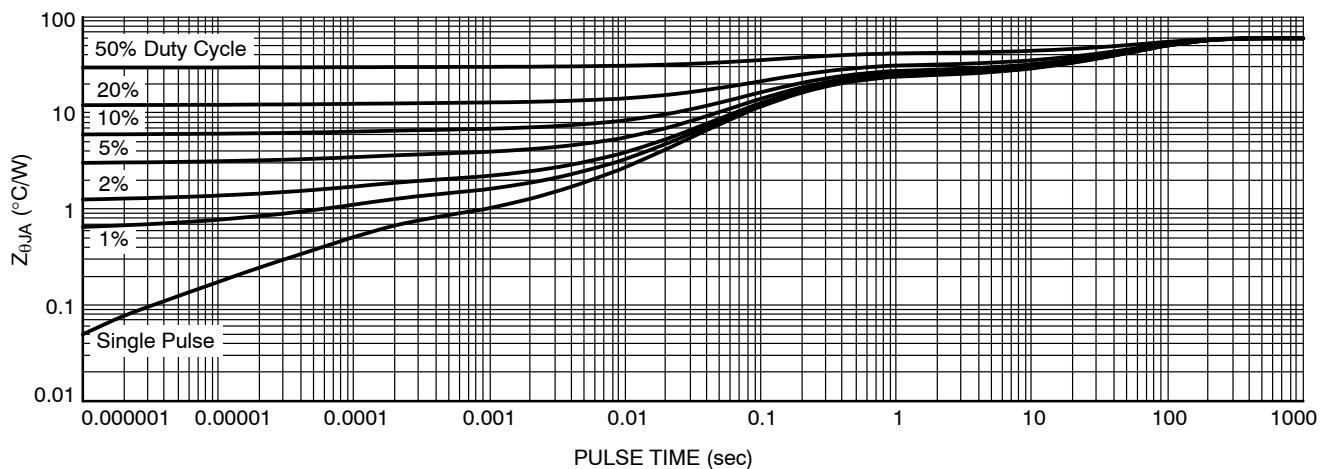


Figure 13. Thermal Characteristics

## DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping <sup>†</sup>
NVTFS016N06CTAG	16NC	μ8FL (Pb-Free)	1500 / Tape & Reel
NVTFWS016N06CTAG	16NW	μ8FL (Pb-Free, Wettable Flanks)	1500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

**MECHANICAL CASE OUTLINE**  
PACKAGE DIMENSIONS

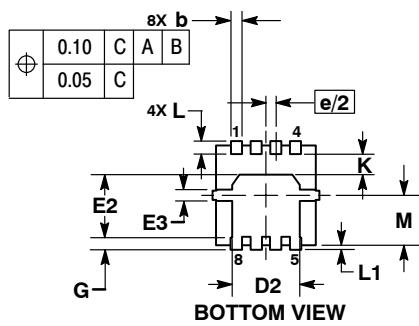
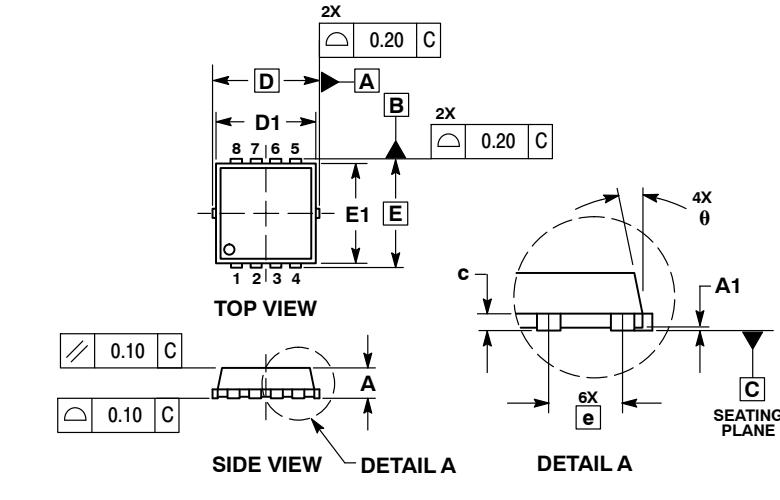
**onsemi**<sup>TM</sup>



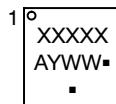
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**WDFN8 3.3x3.3, 0.65P**  
CASE 511AB  
ISSUE D

DATE 23 APR 2012



**GENERIC  
MARKING DIAGRAM\***



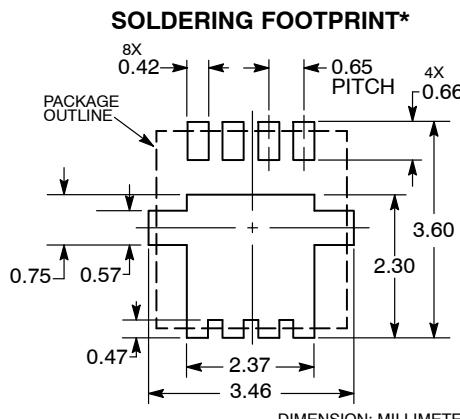
XXXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
■ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.70	0.75	0.80	0.028	0.030	0.031
A1	0.00	---	0.05	0.000	---	0.002
b	0.23	0.30	0.40	0.009	0.012	0.016
c	0.15	0.20	0.25	0.006	0.008	0.010
D	3.30	BSC		0.130	BSC	
D1	2.95	3.05	3.15	0.116	0.120	0.124
D2	1.98	2.11	2.24	0.078	0.083	0.088
E	3.30	BSC		0.130	BSC	
E1	2.95	3.05	3.15	0.116	0.120	0.124
E2	1.47	1.60	1.73	0.058	0.063	0.068
E3	0.23	0.30	0.40	0.009	0.012	0.016
e	0.65	BSC		0.026	BSC	
G	0.30	0.41	0.51	0.012	0.016	0.020
K	0.65	0.80	0.95	0.026	0.032	0.037
L	0.30	0.43	0.56	0.012	0.017	0.022
L1	0.06	0.13	0.20	0.002	0.005	0.008
M	1.40	1.50	1.60	0.055	0.059	0.063
θ	0	°	---	12	°	0



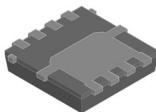
\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WDFN8 3.3x3.3, 0.65P	PAGE 1 OF 1

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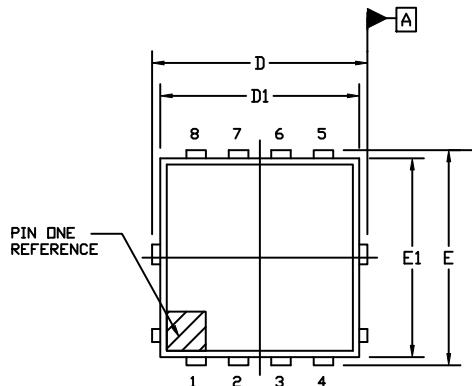
# **MECHANICAL CASE OUTLINE**

## **PACKAGE DIMENSIONS**

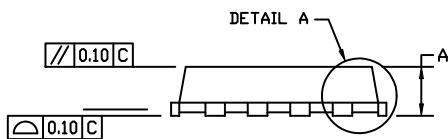


**WDFNW8 3.3x3.3, 0.65P (Full-Cut  $\mu$ 8FL WF)**  
CASE 515AN  
ISSUE O

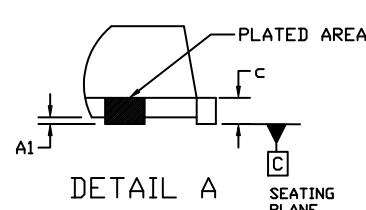
DATE 25 AUG 2020



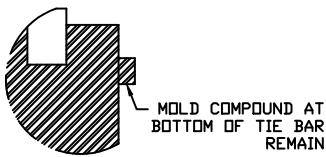
## TOP VIEW



### SIDE VIEW

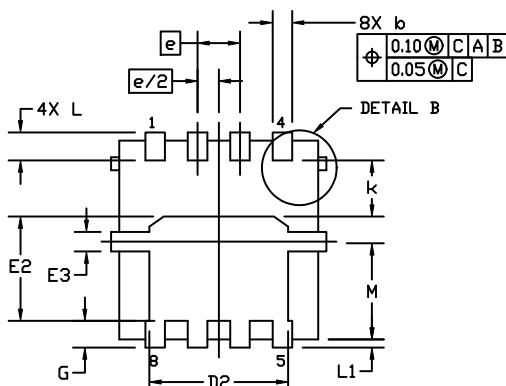


DETAIL A

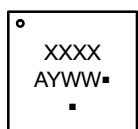


## DETAILS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
A1	0.00	----	0.05
b	0.23	0.30	0.40
c	0.15	0.20	0.25
D	3.05	3.30	3.55
D1	2.95	3.05	3.15
D2	1.98	2.11	2.24
E	3.05	3.30	3.55
E1	2.95	3.05	3.15
E2	1.47	1.60	1.73
E3	0.23	0.30	0.40
e	0.65 BSC		
G	0.30	0.41	0.51
K	0.65	0.80	0.95
L	0.30	0.43	0.59
L1	0.06	0.13	0.20
M	1.40	1.50	1.60

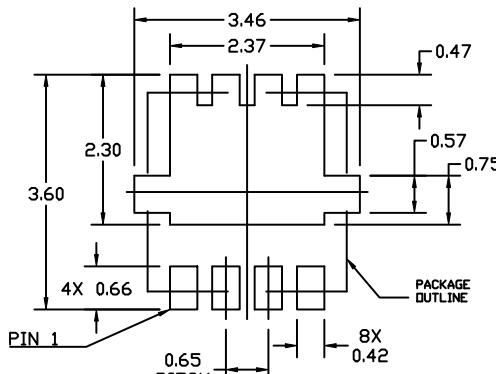


### BOTTOM VIEW



XXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
■ = Pb-Free Package

(Note: Microdot may be in either location)



## RECOMMENDED MOUNTING FOOTPRINT

- \* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOT-REFRM-02.

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>WDFN8 3.3x3.3, 0.65P (Full-Cut <math>\mu</math>8FL WF)</b>	<b>PAGE 1 OF 1</b>

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